

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

CHUNG, et al.

Serial No.: 09/965,370

Confirmation No.: 6507

Filed:

September 26, 2001

For:

Integration of Barrier Layer

and Seed Layer

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Group Art Unit: 1762

Examiner:

Unknown

GROUP 1700

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATE OF MAILING 37 CFR 1 8

I hereby certify that this correspondence is being deposited on July <u>7.1.</u>, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

7/29/03

Signature

Dear Sir:

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

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The Applicants certify that all references submitted with this disclosure were first cited in a communication from a foreign patent office dated May 30, 2003, which communication is enclosed, not more than three months prior to the filing of this Supplemental Information Disclosure Statement.

The Applicant does not feel that a fee is necessary at this time, but if the sum of \$180.00 is due under 37 CFR § 1.17(p) pursuant to § 1.97, the Commissioner is hereby authorized to charge this fee, and any other fee necessary to make this submission timely, to the Deposit Account No. 20-0782/AMAT/6303/CPI/COPPER/PJS/KMT.

Respectfully submitted,

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U.S. Department of Commerce, Patent and Trademark Office					Docket No.		Serial No.	
(PTO Form 1449 modified)					APPM/6303 , , , ,		09/965,370	
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT					APPM/6303 09/965,370  Applicant AU Confirmation No.: CHUNG et al. 0  Filing Date Group			
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U.S. Patent	Docu	ments	T. T.	TE LOCALING ST			T	
*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date I Appropriate	f
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	A15							
Foreign Pat	ent D	ocuments						
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		Number					YES	МО
	B1	EP 0 954 027	11-03-1999	EP	H01L	23/532		X
	B2	WO 00/75964	12-14-2000	WIPO	H01L	-		X
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	B4							
OTHER AR	T							
*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.						
	C1	PCT International Search Report from International Application Number PCT/US02/28715, dated May 30, 2003						

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Date Considered

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.